

replacement paragraph:

B3
The epoxy-containing monomer or resin is preferably blended with one or more thermoplastic materials such as, for example, polyesters, vinyl acetates, ethyl vinyl acetates, polyacrylates, and polycaprolactones. An example of a useful blend is an epoxy-polyester blends described in U.S. patent application entitled "Melt-Flowable Materials and Method of Sealing Surface," filed April 12, 1995 and bearing serial number 08/421,055, incorporated by reference herein. These compositions are melt-flowable (and thus thermoformable) in the uncured state. They feature an epoxy-containing material blended with a semi-crystalline polyester resin. The epoxy-containing material contributes to the ultimate strength and heat resistance of the composition, while the polyester component provides conformability and pliability. The utilization of epoxy-containing based materials with polyester blends is also disclosed in U.S. patent application entitled "Sealant Compositions, Article Including Same, and Method of Using Same" filed on September 30, 1997 and bearing serial number 08/941,430, now U.S. Patent No. 6,284,360, incorporated by reference herein. An example of ethyl vinyl acetates includes those disclosed in U.S. patent application entitled "Epoxy/Thermoplastic Photocurable Adhesive Compositions" filed May 1, 1998 and bearing serial number 09/070,971, now U.S. Patent No. 6,057,382, incorporated by reference herein.

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Please replace the paragraph on page 12, lines 9-14 with the following replacement paragraph:

B4
In certain cases, it may be advantageous to add an accelerator to the composition. An accelerator added to one or both of the adhesive layers and the bulk layer can affect the curing rate and thereby achieve the desirable results of the present invention. Dihydroxy aromatics, such as those disclosed in U.S. Patent Application Serial No. 09/224,421 filed December 31, 1998, now U.S. Patent No. 6,133,335, herein incorporated by reference in its entirety, are suitable for use in the present invention.

✓
Please replace the paragraph on page 17, lines 1-3 with the following replacement paragraph:

B5
The optional core layer can also be prepared in many ways, depending on its composition. Methods suitable for use with the invention are disclosed in U.S. Patent Application Serial No. 08/941,430, now U.S. Patent No. 6,284,360, previously incorporated by reference.